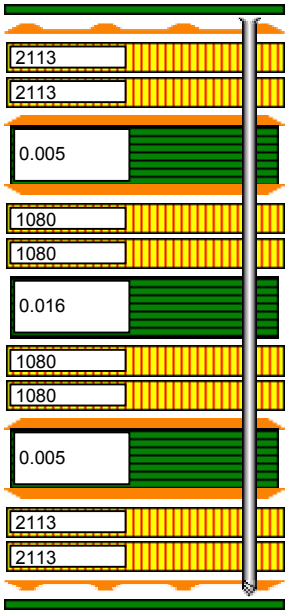
Building Tomorrow's Technology... Today

**Customer :** Texas Instruments
**Part Num :** DAC31X2EVM
**Part Rev :** B

**Job Name :** TI_DAC31X2EVM
**Engineer :** David Gorden
**Facility :** Toronto

| Layer | Calc Thickness | Primary Stack | Description |
|---|---|---|---|
| | 0.0005 |  | Taiyo 4000-MP |
| Layer - 1 | 0.0020 | | **1/2oz Sig (Std Plt)** |
| | 0.0077 | | N4000-13 |
| Layer - 2 | 0.0012 | | **1oz P/G** |
| | 0.0050 | | N4000-13 |
| Layer - 3 | 0.0012 | | **1oz P/G** |
| | 0.0059 | | N4000-13 |
| | 0.0160 | | N4000-13 |
| | 0.0059 | | N4000-13 |
| Layer - 4 | 0.0012 | | **1oz P/G** |
| | 0.0050 | | N4000-13 |
| Layer - 5 | 0.0012 | | **1oz P/G** |
| | 0.0077 | | N4000-13 |
| Layer - 6 | 0.0020 | | **1/2oz Sig (Std Plt)** |
| | 0.0005 | | Taiyo 4000-MP |



| Requirement | Req. Thickness | Tol + | Tol - | Calc Thick |
|---|---|---|---|---|
| Incl. Plating & Mask | 0.0620 | 0.0062 | 0.0062 | 0.0630 |
| Incl. Mask over Laminate | 0.0580 | 0.0058 | 0.0058 | 0.0590 |
| Incl. Plating | 0.0610 | 0.0061 | 0.0061 | 0.0620 |
| After Lamination | 0.0582 | 0.0029 | 0.0029 | 0.0592 |
| Over Laminate | 0.0570 | 0.0057 | 0.0057 | 0.0580 |

| Impedance Type | Layer | Design | Actual | Pitch | Plane | Target | Tol | Predict |
|---|---|---|---|---|---|---|---|---|
| 1 Surface MS | L1 | 0.0150 | 0.0150 | - | - | 50 | 5.0 | 49.58 |
| | - | - | - | - | L2 | | | |
| 2 EC Microstrip | L1 | 0.0070 | 0.0075 | 0.0130 | - | 100 | 10.0 | 99.37 |
| | - | 0.0070 | 0.0075 | - | L2 | | | |
| 3 Surface MS | L6 | 0.0150 | 0.0150 | - | L5 | 50 | 5.0 | 49.58 |
| | - | - | - | - | - | | | |
| 4 EC Microstrip | L6 | 0.0070 | 0.0075 | 0.0130 | L5 | 100 | 10.0 | 99.37 |
| | - | 0.0070 | 0.0075 | - | - | | | |